

## ABSTRACT

A process for producing at least one electrical contacting pad on a receiving zone (2) of an electronic component is disclosed herein. The process includes injecting a liquid alloy or metal (4) into at least one channel (5) comprising a feed portion (5A) and a molding portion (5B) which are separated by a narrowing. The channel (5) is positioned in such a way that the molding portion (5B) opens on the receiving zone (2). The process further includes separating the molding portion (5B) from the receiving zone (2) before complete solidification of the liquid alloy or metal (4), while the feed (5A) and molding (5B) portions remain joined. The feed portion (5A) is part of a first part forming a die (6), and the molding portion (5B) is part of a second separate part forming a mold (7). The die and mold are juxtaposed to form the channel (5).